MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Power Supply Voltage	V_{CC}	+36 or ±18	Vdc
Input Differential Voltage Range	V_{IDR}	36	Vdc
Input Common Mode Voltage Range	V_{ICR}	−0.3 to +36	Vdc
Output Short Circuit−to−Ground Output Sink Current (Note 1)	I_{SC} I_{Sink}	Continuous 20	mA
Power Dissipation @ T_A = 25°C Derate above 25°C	P_D $1/R_{\theta JA}$	570 5.7	mW mW/°C
Operating Ambient Temperature Range LM293 LM393 LM2903 LM2903V, NCV2903 (Note 2)	T_A	 −25 to +85 0 to +70 −40 to +105 −40 to +125	°C
Maximum Operating Junction Temperature LM393, 2903, LM2903V LM293, NCV2903	$T_{J(max)}$	 150 150	°C
Storage Temperature Range	T_{stg}	−65 to +150	°C
ESD Protection at any Pin (Note 3) − Human Body Model − Machine Model	V_{ESD}	 1500 150	V

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

1. The maximum output current may be as high as 20 mA, independent of the magnitude of V_{CC}, output short circuits to V_{CC} can cause excessive heating and eventual destruction.
2. *NCV2903 is qualified for automotive use.*
3. V_{ESD} rating for NCV/SC devices is: Human Body Model − 2000 V; Machine Model − 200 V.

ELECTRICAL CHARACTERISTICS (V_{CC} = 5.0 Vdc, $T_{low} \le T_A \le T_{high}$, unless otherwise noted.)

Characteristic	Symbol	LM293, LM393			LM2903, LM2903V, NCV2903			Unit
		Min	Typ	Max	Min	Typ	Max	
Input Offset Voltage (Note 5)	V_{IO}							mV
T_A = 25°C		–	±1.0	±5.0	–	±2.0	±7.0	
$T_{low} \le T_A \le T_{high}$		–	–	9.0	–	9.0	15	
Input Offset Current	I_{IO}							nA
T_A = 25°C		–	±5.0	±50	–	±5.0	±50	
$T_{low} \le T_A \le T_{high}$		–	–	±150	–	±50	±200	
Input Bias Current (Note 6)	I_{IB}							nA
T_A = 25°C		–	25	250	–	25	250	
$T_{low} \le T_A \le T_{high}$		–	–	400	–	200	500	
Input Common Mode Voltage Range (Note 6)	V_{ICR}							V
T_A = 25°C		0	–	V_{CC} −1.5	0	–	V_{CC} −1.5	
$T_{low} \le T_A \le T_{high}$		0	–	V_{CC} −2.0	0	–	V_{CC} −2.0	
Voltage Gain $R_L \ge$ 15 kΩ, V_{CC} = 15 Vdc, T_A = 25°C	A_{VOL}	50	200	–	25	200	–	V/mV
Large Signal Response Time V_{in} = TTL Logic Swing, V_{ref} = 1.4 Vdc V_{RL} = 5.0 Vdc, R_L = 5.1 kΩ, T_A = 25°C	–	–	300	–	–	300	–	ns
Response Time (Note 8) V_{RL} = 5.0 Vdc, R_L = 5.1 kΩ, T_A = 25°C	t_{TLH}	–	1.3	–	–	1.5	–	μs
Input Differential Voltage (Note 9) All $V_{in} \ge$ GND or V− Supply (if used)	V_{ID}	–	–	V_{CC}	–	–	V_{CC}	V
Output Sink Current $V_{in} \ge$ 1.0 Vdc, V_{in+} = 0 Vdc, $V_O \le$ 1.5 Vdc T_A = 25°C	I_{Sink}	6.0	16	–	6.0	16	–	mA
Output Saturation Voltage	V_{OL}							mV
$V_{in} \ge$ 1.0 Vdc, V_{in+} = 0, $I_{Sink} \le$ 4.0 mA, T_A = 25°C		–	150	400	–	–	400	
$T_{low} \le T_A \le T_{high}$		–	–	700	–	200	700	
Output Leakage Current	I_{OL}							nA
V_{in-} = 0 V, $V_{in+} \ge$ 1.0 Vdc, V_O = 5.0 Vdc, T_A = 25°C		–	0.1	–	–	0.1	–	
V_{in-} = 0 V, $V_{in+} \ge$ 1.0 Vdc, V_O = 30 Vdc, $T_{low} \le T_A \le T_{high}$		–	–	1000	–	–	1000	
Supply Current	I_{CC}							mA
R_L = ∞ Both Comparators, T_A = 25°C		–	0.4	1.0	–	0.4	1.0	
R_L = ∞ Both Comparators, V_{CC} = 30 V		–	–	2.5	–	–	2.5	

LM293 T_{low} = −25°C, T_{high} = +85°C
LM393 T_{low} = 0°C, T_{high} = +70°C
LM2903 T_{low} = −40°C, T_{high} = +105°C
LM2903V & NCV2903 T_{low} = −40°C, T_{high} = +125°C
NCV2903 is qualified for automotive use.

4. The maximum output current may be as high as 20 mA, independent of the magnitude of V_{CC}, output short circuits to V_{CC} can cause excessive heating and eventual destruction.
5. At output switch point, $V_O \simeq$ 1.4 Vdc, R_S = 0 Ω with V_{CC} from 5.0 Vdc to 30 Vdc, and over the full input common mode range (0 V to V_{CC} = −1.5 V).
6. Due to the PNP transistor inputs, bias current will flow out of the inputs. This current is essentially constant, independent of the output state, therefore, no loading changes will exist on the input lines.
7. Input common mode of either input should not be permitted to go more than 0.3 V negative of ground or minus supply. The upper limit of common mode range is V_{CC} −1.5 V.
8. Response time is specified with a 100 mV step and 5.0 mV of overdrive. With larger magnitudes of overdrive faster response times are obtainable.
9. The comparator will exhibit proper output state if one of the inputs becomes greater than V_{CC}, the other input must remain within the common mode range. The low input state must not be less than −0.3 V of ground or minus supply.

LM293/393

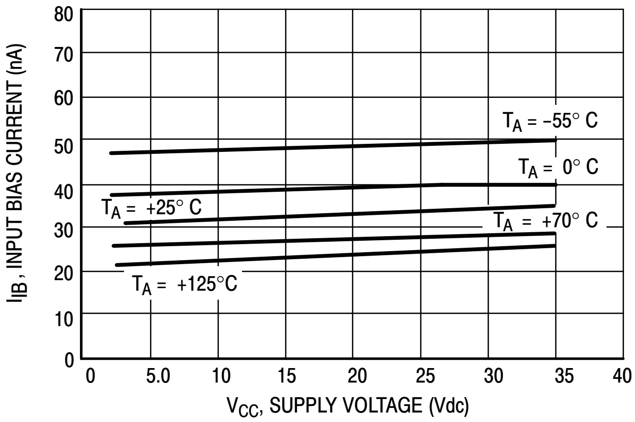


Figure 2. Input Bias Current versus Power Supply Voltage

LM2903

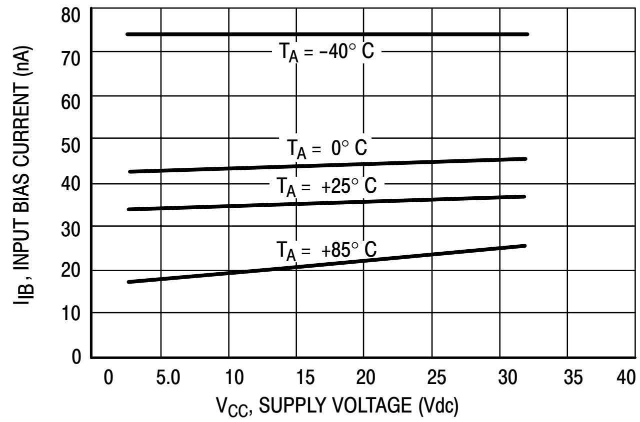


Figure 3. Input Bias Current versus Power Supply Voltage

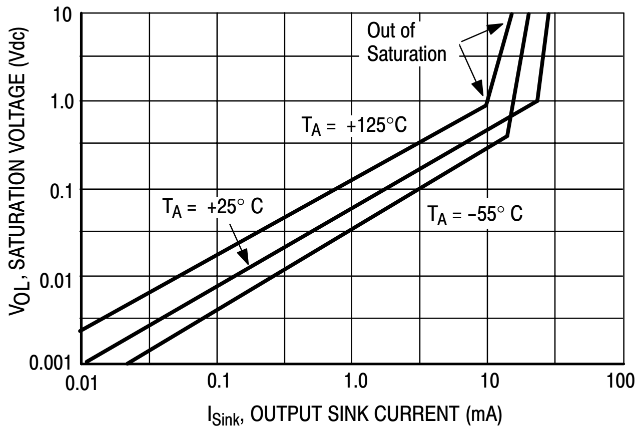


Figure 4. Output Saturation Voltage versus Output Sink Current

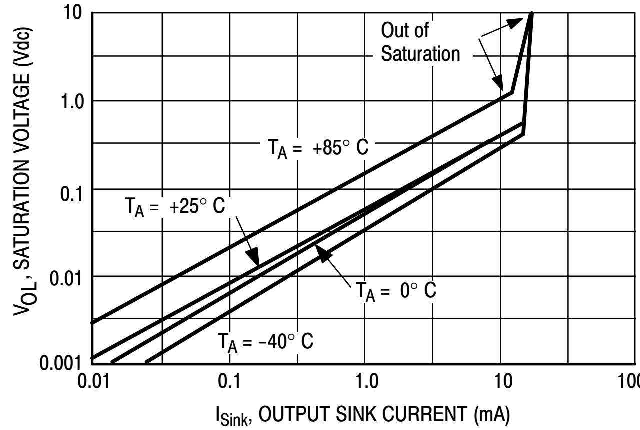


Figure 5. Output Saturation Voltage versus Output Sink Current

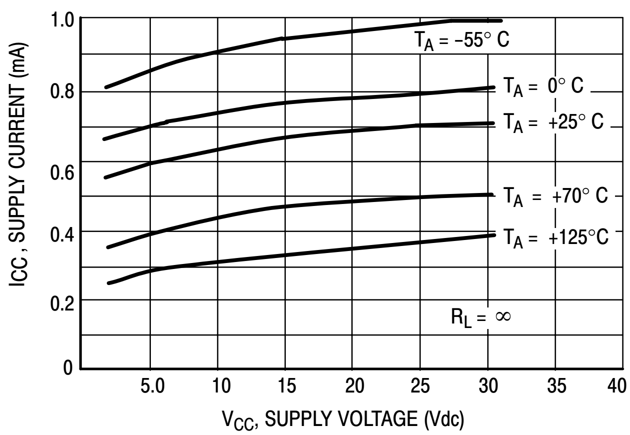


Figure 6. Power Supply Current versus Power Supply Voltage

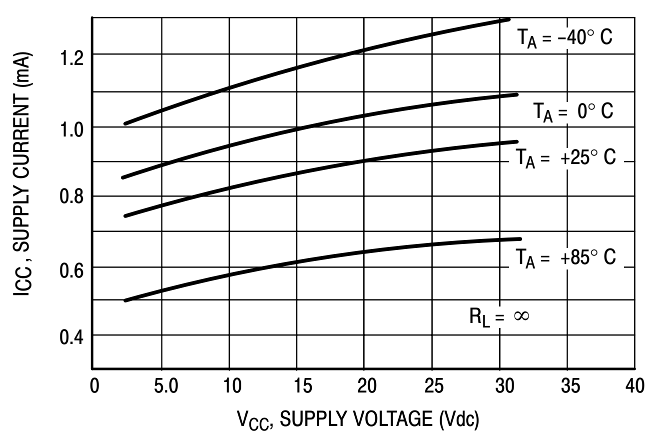


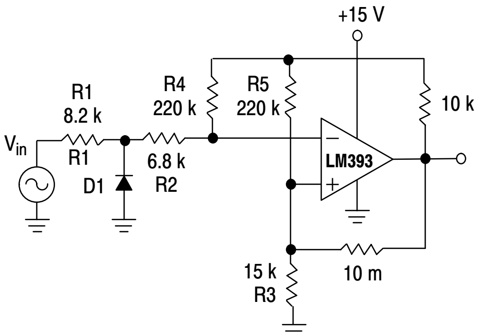
Figure 7. Power Supply Current versus Power Supply Voltage

APPLICATIONS INFORMATION

These dual comparators feature high gain, wide bandwidth characteristics. This gives the device oscillation tendencies if the outputs are capacitively coupled to the inputs via stray capacitance. This oscillation manifests itself during output transitions (V_{OL} to V_{OH}). To alleviate this situation, input resistors < 10 kΩ should be used.

The addition of positive feedback (< 10 mV) is also recommended. It is good design practice to ground all unused pins.

Differential input voltages may be larger than supply voltage without damaging the comparator's inputs. Voltages more negative than −0.3 V should not be used.

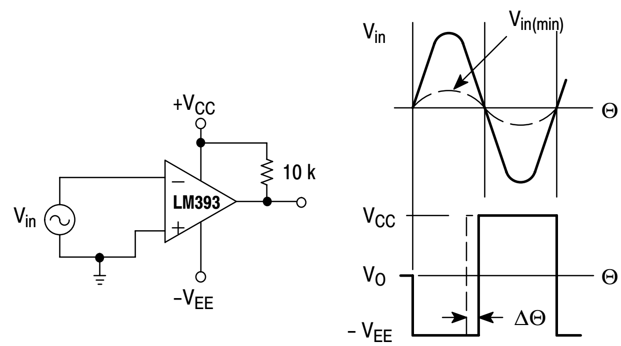


D1 prevents input from going negative by more than 0.6 V.

$$R1 + R2 = R3$$

$$R3 \leq \frac{R5}{10} \text{ for small error in zero crossing.}$$

Figure 8. Zero Crossing Detector (Single Supply)



$V_{in(min)} \approx$ 0.4 V peak for 1% phase distortion (ΔΘ).

Figure 9. Zero Crossing Detector (Split Supply)

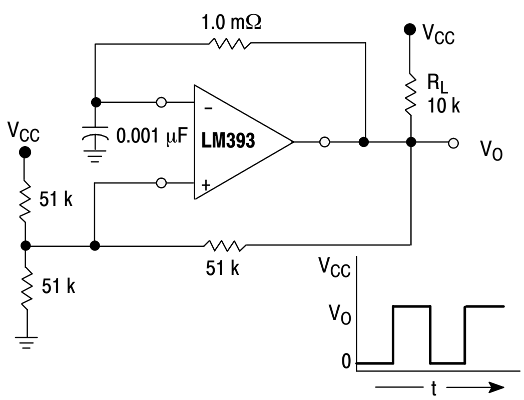
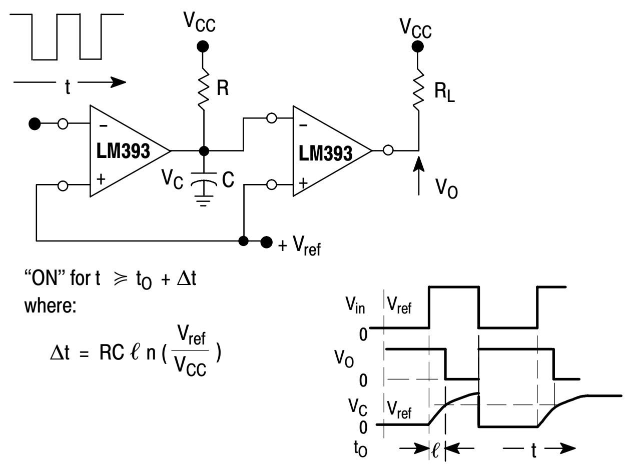


Figure 10. Free−Running Square−Wave Oscillator

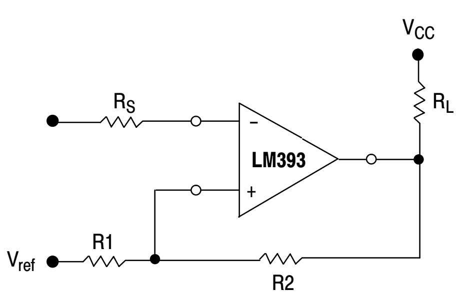


"ON" for $t \geqslant t_O + \Delta t$

where:

$$\Delta t = RC \, \ell n \left(\frac{V_{ref}}{V_{CC}} \right)$$

Figure 11. Time Delay Generator



$$R_S = R1 \,||\, R2$$

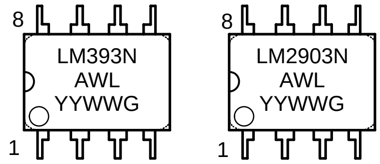
$$V_{th1} = V_{ref} + \frac{(V_{CC} - V_{ref})\,R1}{R1 + R2 + R_L}$$

$$V_{th2} = V_{ref} - \frac{(V_{ref} - V_O\,\text{Low})\,R1}{R1 + R2}$$

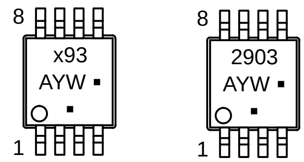
Figure 12. Comparator with Hysteresis

MARKING DIAGRAMS

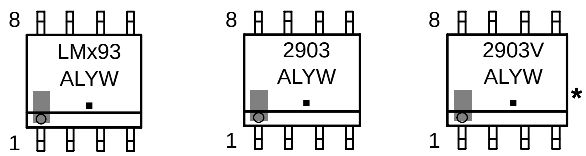
PDIP−8
N SUFFIX
CASE 626



Micro8
DM SUFFIX
CASE 846A



SOIC−8
D SUFFIX
CASE 751



x	= 2 or 3
A	= Assembly Location
WL, L	= Wafer Lot
YY, Y	= Year
WW, W	= Work Week
▪, G	= Pb−Free Package

(Note: Microdot may be in either location)
*This marking diagram also applies to NCV2903DR2.

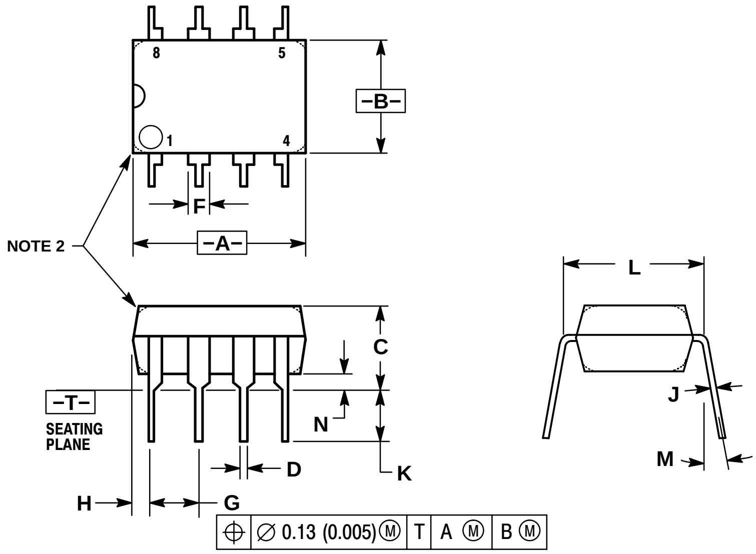
ORDERING INFORMATION

Device	Package	Shipping†
LM293D	SOIC−8	98 Units / Rail
LM293DG	SOIC−8 (Pb−Free)	98 Units / Rail
LM293DR2	SOIC−8	2500 / Tape & Reel
LM293DR2G	SOIC−8 (Pb−Free)	2500 / Tape & Reel
LM293DMR2	Micro8	4000 / Tape and Reel
LM293DMR2G	Micro8 (Pb−Free)	4000 / Tape and Reel
LM393D	SOIC−8	98 Units / Rail
LM393DG	SOIC−8 (Pb−Free)	98 Units / Rail
LM393DR2	SOIC−8	2500 / Tape & Reel
LM393DR2G	SOIC−8 (Pb−Free)	2500 / Tape & Reel
LM393N	PDIP−8	50 Units / Rail
LM393NG	PDIP−8 (Pb−Free)	50 Units / Rail
LM393DMR2	Micro8	4000 / Tape and Reel
LM393DMR2G	Micro8 (Pb−Free)	4000 / Tape and Reel
LM2903D	SOIC−8	98 Units / Rail
LM2903DG	SOIC−8 (Pb−Free)	98 Units / Rail
LM2903DR2	SOIC−8	2500 / Tape & Reel
LM2903DR2G	SOIC−8 (Pb−Free)	2500 / Tape & Reel
LM2903N	PDIP−8	50 Units / Rail
LM2903NG	PDIP−8 (Pb−Free)	50 Units / Rail
LM2903DMR2	Micro8	4000 / Tape and Reel
LM2903DMR2G	Micro8 (Pb−Free)	4000 / Tape and Reel
LM2903VD	SOIC−8	98 Units / Rail
LM2903VDG	SOIC−8 (Pb−Free)	98 Units / Rail
LM2903VDR2	SOIC−8	2500 / Tape & Reel
LM2903VDR2G	SOIC−8 (Pb−Free)	2500 / Tape & Reel
LM2903VN	PDIP−8	50 Units / Rail
LM2903VNG	PDIP−8 (Pb−Free)	50 Units / Rail
NCV2903DR2 (Note 10)	SOIC−8	2500 / Tape & Reel
NCV2903DR2G (Note 10)	SOIC−8 (Pb−Free)	2500 / Tape & Reel
NCV2903DMR2 (Note 10)	Micro8	4000 / Tape & Reel
NCV2903DMR2G (Note 10)	Micro8 (Pb−Free)	4000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.
10. NCV2903 is qualified for automotive use.

PACKAGE DIMENSIONS

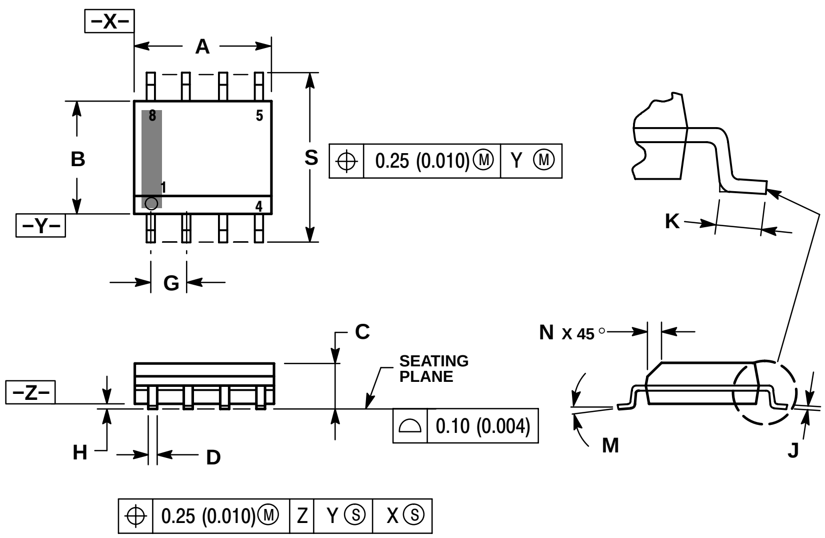
PDIP−8
N SUFFIX
CASE 626−05
ISSUE L



NOTES:
1. DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.
2. PACKAGE CONTOUR OPTIONAL (ROUND OR SQUARE CORNERS).
3. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	9.40	10.16	0.370	0.400
B	6.10	6.60	0.240	0.260
C	3.94	4.45	0.155	0.175
D	0.38	0.51	0.015	0.020
F	1.02	1.78	0.040	0.070
G	2.54 BSC		0.100 BSC	
H	0.76	1.27	0.030	0.050
J	0.20	0.30	0.008	0.012
K	2.92	3.43	0.115	0.135
L	7.62 BSC		0.300 BSC	
M	---	10°	---	10°
N	0.76	1.01	0.030	0.040

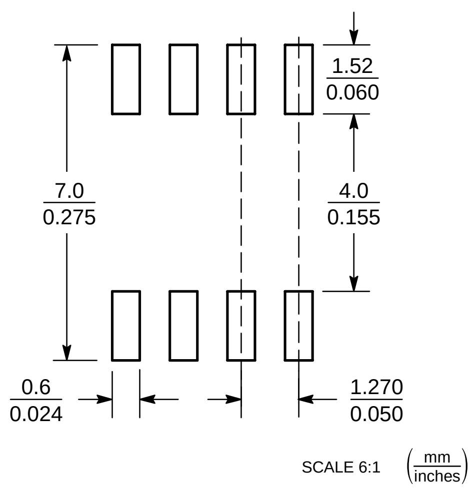
SOIC−8
D SUFFIX
CASE 751−07
ISSUE AG



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. 751−01 THRU 751−06 ARE OBSOLETE. NEW STANDARD IS 751−07.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	4.80	5.00	0.189	0.197
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.053	0.069
D	0.33	0.51	0.013	0.020
G	1.27 BSC		0.050 BSC	
H	0.10	0.25	0.004	0.010
J	0.19	0.25	0.007	0.010
K	0.40	1.27	0.016	0.050
M	0 °	8 °	0 °	8 °
N	0.25	0.50	0.010	0.020
S	5.80	6.20	0.228	0.244

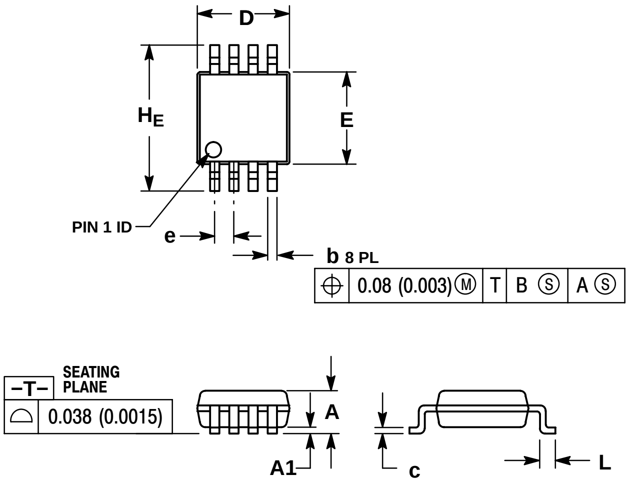
SOLDERING FOOTPRINT*



*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

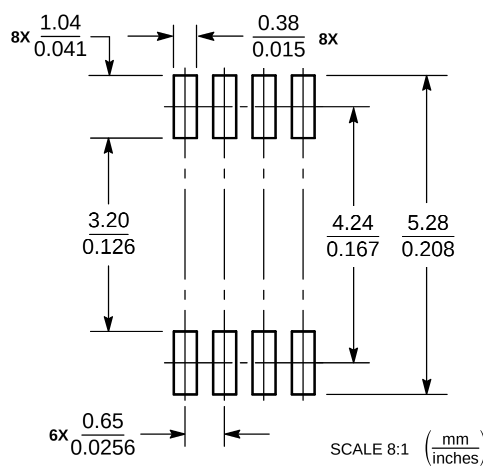
Micro8
DM SUFFIX
CASE 846A−02
ISSUE G



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. 846A-01 OBSOLETE, NEW STANDARD 846A-02.

	MILLIMETERS			INCHES		
DIM	**MIN**	**NOM**	**MAX**	**MIN**	**NOM**	**MAX**
A	−−	−−	1.10	−−	−−	0.043
A1	0.05	0.08	0.15	0.002	0.003	0.006
b	0.25	0.33	0.40	0.010	0.013	0.016
c	0.13	0.18	0.23	0.005	0.007	0.009
D	2.90	3.00	3.10	0.114	0.118	0.122
E	2.90	3.00	3.10	0.114	0.118	0.122
e	0.65 BSC			0.026 BSC		
L	0.40	0.55	0.70	0.016	0.021	0.028
H_E	4.75	4.90	5.05	0.187	0.193	0.199

SOLDERING FOOTPRINT*



*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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